

VGA, CMOS, Time of Flight, Backside Illumination Sensor

FEATURES

- ▶ 512 (horizontal) × 640 (vertical) pixel array
- ▶ 3.5 μm × 3.5 μm square pixels
- ▶ 1/6 inch optical format
- ▶ 4-wire SPI or 2-wire I²C serial interface
- ▶ MIPI CSI-2 transmitter interface with support for 1 or 2 data lanes, programmable up to 2.5 Gbps per lane
- ▶ Dual, 3.3 V and 1.2 V external supplies, 1.8 V input and output section
- ▶ Die size: 3.749 mm ± 0.01 mm × 6.4544 mm ± 0.01 mm

APPLICATIONS

- ▶ Smartphones
- ▶ Augmented reality (AR) and virtual reality (VR)
- ▶ Machine vision systems (logistics and inventory)
- ▶ Robotics (consumer and industrial)

FUNCTIONAL BLOCK DIAGRAM

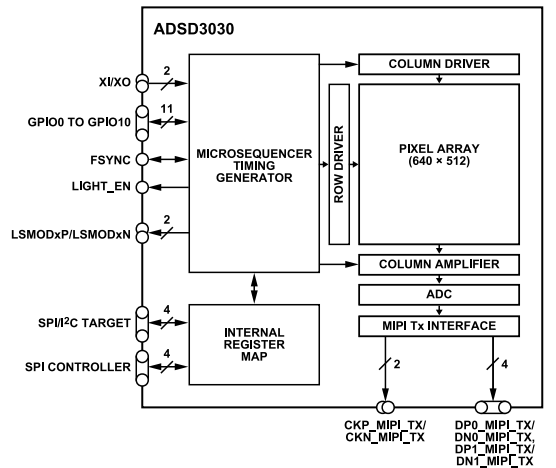


Figure 1. Functional Block Diagram

For more information about the ADSD3030, contact the Analog Devices, Inc., at tof@analog.com.

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